CLAIMS

1. A polishing composition comprising:

silica having an organic acid immobilized on a surface thereof;

a dihydric alcohol having a molecular weight in the range of 400 to 2000; and

a pH adjusting agent,

the polishing composition having a pH of 6 or less.

2. The polishing composition according to claim 1, wherein the organic acid is sulfonic acid or carboxylic acid.

3. The polishing composition according to claim 1 or 2, wherein the dihydric alcohol is polyethylene glycol.

4. The polishing composition according to any one of claims 1 to 3, wherein a pH is 4 or less.

5. The polishing composition according to any one of claims 1 to 4, wherein the polishing composition is used to polish a material to be polished having a polishing object and a layer containing a material different from the polishing object.

6. The polishing composition according to claim 5, wherein the polishing object is silicon nitride and the layer containing a material different from the polishing object contains at least either of polycrystalline silicon or tetraethyl orthosilicate.

7. The polishing composition according to any one of claims 1 to 6, wherein a content of silica having an organic acid immobilized on the surface is 0.005% by weight or more and 1% by weight or

less.

8. A polishing method comprising:

a step of polishing a material to be polished by using the polishing composition according to any one of claims 1 to 7, wherein the material to be polished has a polishing object and a layer containing a material different from the polishing object.

9. A method for producing a substrate, comprising:

a step of polishing a material to be polished by the polishing method according to claim 8, wherein the material to be polished has a polishing object and a material different from the polishing object.